



Material Content Data Sheet



Sales Product Name		ICE2QS02G		Issued		19. July 2018		
MA#		MA001040346						
Package		PG-DSO-8-41		Weight*		80.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.697	2.10	2.10	20998	20998
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		416	
	non noble metal	iron	7439-89-6	0.673	0.83		8329	
wire	non noble metal	copper	7440-50-8	27.330	33.82	34.70	338199	347048
	noble metal	gold	7440-57-5	0.119	0.15	0.15	1468	1468
	encapsulation	organic material	carbon black	1333-86-4	0.147	0.18		1816
encapsulation	plastics	epoxy resin	-	4.745	5.87		58715	
	inorganic material	silicondioxide	60676-86-0	44.024	54.48	60.53	544775	605306
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10071	10071
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1108	1108
glue	plastics	acrylic resin	-	0.226	0.28		2800	
	noble metal	silver	7440-22-4	0.905	1.12	1.40	11201	14001
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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